Test Bank for Electronics for Electricians 7th Edition by Herman ISBN 1305505999 9781305505995

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Solution Manual

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Unit 2 — Power Rating and Heat Sinking Components

TRUE/FALSE

1.	. Heat sinks vary in size and shape, but have only one purpose.				e purpose.	
	ANS: T	PTS:	1	REF:	Heat Sinks	
2.	. The purpose of a heat sink is to decrease the surface area of the device connected to it.					
	ANS: F	PTS:	1	REF:	Heat Sinks	
3.	The surface of the de	vice and	l heat sink may	y look p	erfectly flat to the naked eye.	
	ANS: T	PTS:	1	REF:	Heat Sinks	
4.	4. Using thermal compound when heat sinking components is not a necessity.					
	ANS: F	PTS:	1	REF:	Heat Sinks	
5.	5. Small heat sinks are generally used when a component is operated at its lowest power rating.					
	ANS: F	PTS:	1	REF:	Heat Sinks	
MUL	FIPLE CHOICE					
1. Electrical and electronic components have a power rating measured in						
	a. volts			c.	watts	
	b. ohms			d.	amps	
	ANS: C	PTS:	1	REF:	Power Rating	
2.	Therating indi	cates the	e amount of he	at that t	he component can dissipate before damage occurs.	
	a. power			c.	resistance	
	b. energy			d.	current	
	ANS: A	PTS:	1	REF:	Power Rating	
3.	The thermal compou	nd that	is greasy and g	enerall	y white in color is made from	
	a. sodium oxide				beryllium perchlorate	
	b. magnesium perc	oxide		d.	beryllium oxide	

ANS: D **PTS**: 1 REF: Heat Sinks

4. When a compone	nt is mounted to a hea	at sink,is generally used to ensure a good thermal contact				
between the device and the heat sink.						
a. thermal com	pound	c. resistance compound				
b. insulation co	mpound	d. break compound				
ANS: A	PTS: 1	REF: Heat Sinks				

5. _____is used to fill in the gaps between the two surfaces and provide good thermal contact. a. Insulation compound c. Break compound

- c. Break compound

b. Thermal compound

d. Lock compound

ANS: B PTS: 1

REF: Heat Sinks